



Compact Models for Double Gate (DG) MOSFET with Quantum Mechanical Effects Using Lambert Function



Henok Abebe

*MOSIS, Information Sciences Institute
Viterbi School of Engineering
University of Southern California*

Co-authors

Ellis Cumberbatch: *CGU School of Mathematical Sciences*
Hedley Morris: *CGU School of Mathematical Sciences*
Vance Tyree: *USC/ISI MOSIS*

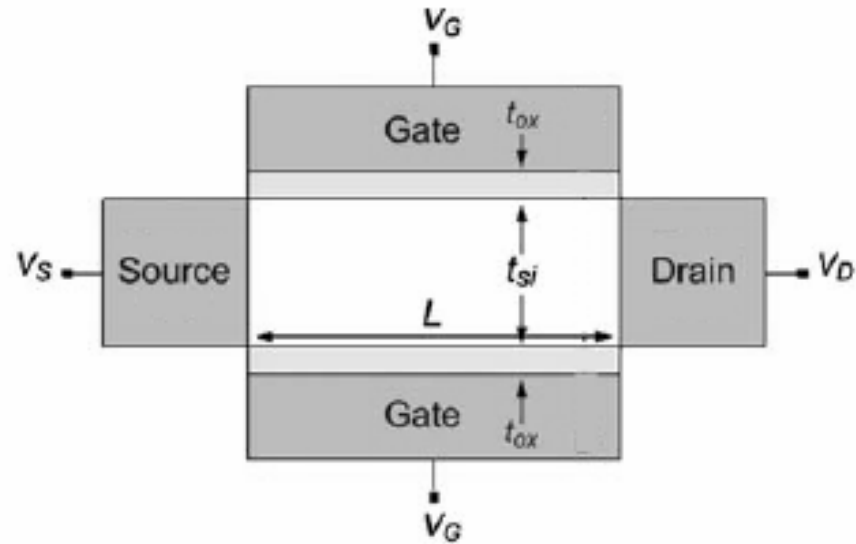


Outline

- DG MOSFET.
 - Model equations.
 - Iteration method using Lambert function.
 - Compact quantum model for DG.
 - Self-Consistent Schrödinger-Poisson (SP) numerical approach.
 - Results and comparison.
- } Review



DG MOSFET



- The above double gate device structure is considered.



DG MOSFET (continues)

- Undoped and symmetric.

Relatively small silicon thickness $t_{si}=5\text{nm}$ and $t_{si}=20\text{nm}$.

The two gate voltages are considered to be the same, V_g .

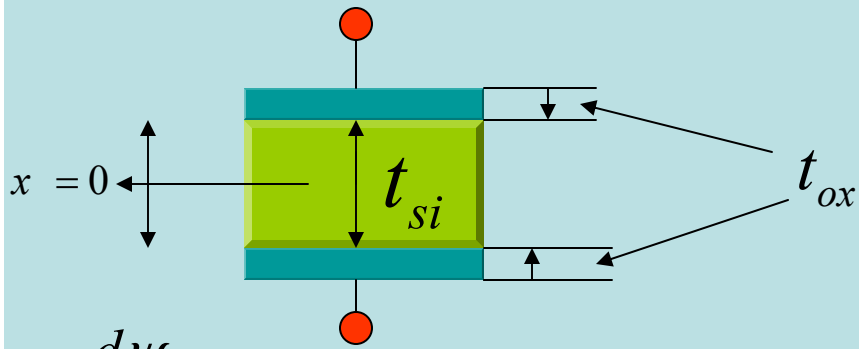
- Thin gate oxide $t_{ox}=1.5\text{nm}$

Quantum confinement effect is significant.



Model equations

- Boundary conditions



- Poisson equation

$$\frac{d^2\psi}{dx^2} = \frac{q}{\epsilon_{si}} n_i e^{q(\psi-V)/kT}$$

- $\frac{d\psi}{dx} \Big|_{x=0} = 0$

- $\psi(x=0) = \psi_0$

- $C_{ox} (V_g - \Delta\phi - \psi(\pm t_{si}/2)) = \pm \epsilon_{si} \frac{d\psi}{dx} \Big|_{x=\pm t_{si}/2}$

where $C_{ox} = \epsilon_{ox} / t_{ox}$



Model equations (continues)

- Exact solution using the first two boundary conditions:

$$\psi(x) = V + \psi_0 - \frac{2kT}{q} \ln \left[\cos \left(\sqrt{\frac{q^2 n_i}{2\epsilon_{si} kT}} e^{q\psi_0/2kT} x \right) \right]$$

- The surface potential:

$$\psi_s = \psi(t_{si} / 2)$$



Model equations (continues)

- The interface boundary condition \longrightarrow equation for β :

$$\ln \beta - \ln(\cos \beta) + 2r \beta \tan \beta = v$$

$$v = \frac{q(V_g - \Delta\phi - V)}{2kT} - \ln\left(\frac{2}{t_{si}} \sqrt{\frac{2\varepsilon_{si}kT}{q^2 n_i}}\right)$$

$$\text{where } \beta = \frac{t_{si}}{2} \sqrt{\frac{q^2 n_i}{2kT\varepsilon_{si}}} e^{q\psi_0/2kT} \text{ and } r = \frac{\varepsilon_{si} t_{ox}}{\varepsilon_{ox} t_{si}}$$



Model equations (continues)

- The total mobile charge per unit gate area:

$$Q = 2\epsilon_{si} (d\psi / dx)_{x=t_{si}/2} = 2\epsilon_{si} (2kT/q)(2\beta/t_{si}) \tan\beta$$

- The channel current:

$$I_{ds} = I_{ds0} \left[\beta \tan\beta - \frac{1}{2} \beta^2 + r\beta^2 \tan^2\beta \right]_{\beta_D}^{\beta_S}$$

$$\text{where } I_{ds0} = \mu \frac{W}{L} \frac{4\epsilon_{si}}{t_{si}} \left(\frac{2kT}{q} \right)^2$$

$$\text{and } 0 < \beta < \pi/2$$



Iteration method using Lambert function

•Recast $\ln(\beta \sec \beta) + 2r\beta \tan \beta = v$

as $(2rz)e^{2rz} = x$ where $z = \beta \tan \beta$ and $x = (2r \sin \beta)e^v$

to give $\beta = \Phi\left[\frac{1}{2r} \text{Lambert}W(x)\right]$ where $z = \Phi \tan \Phi$

Lambert $W(x)$ function is the solution of $x = We^W$



Iteration method (continues)

$$\Phi(z) = \Phi_0 - \frac{(\Phi_0 \tan \Phi_0 - z)}{\tan \Phi_0 + \Phi_0 \sec^2 \Phi_0}$$

- where

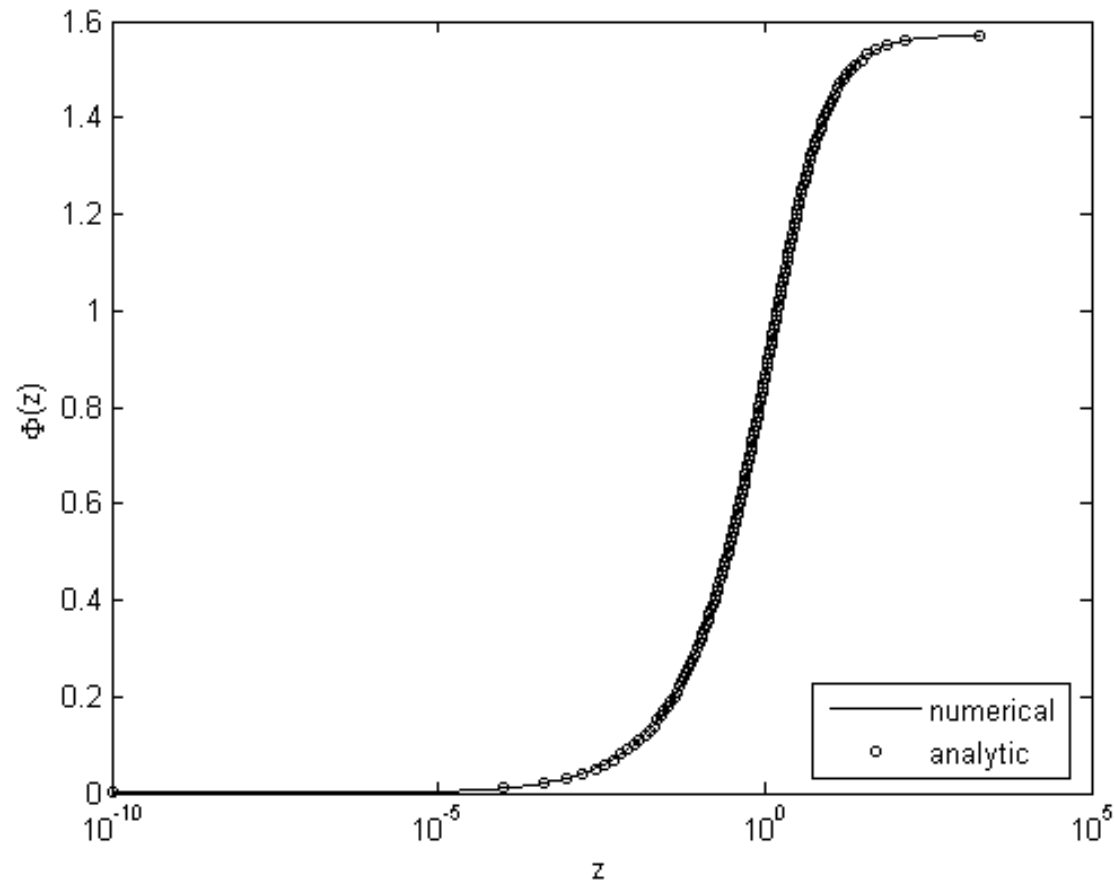
$$\Phi_0 = \sqrt{\frac{(1 + z\gamma) - \sqrt{(z\gamma - 1)^2 - 4z(z\delta - 1/3)}}{2(z\delta + \gamma - 1/3)}},$$

$$\gamma = \frac{40}{9\pi^2} \text{ and } \delta = \frac{16}{9\pi^4}$$



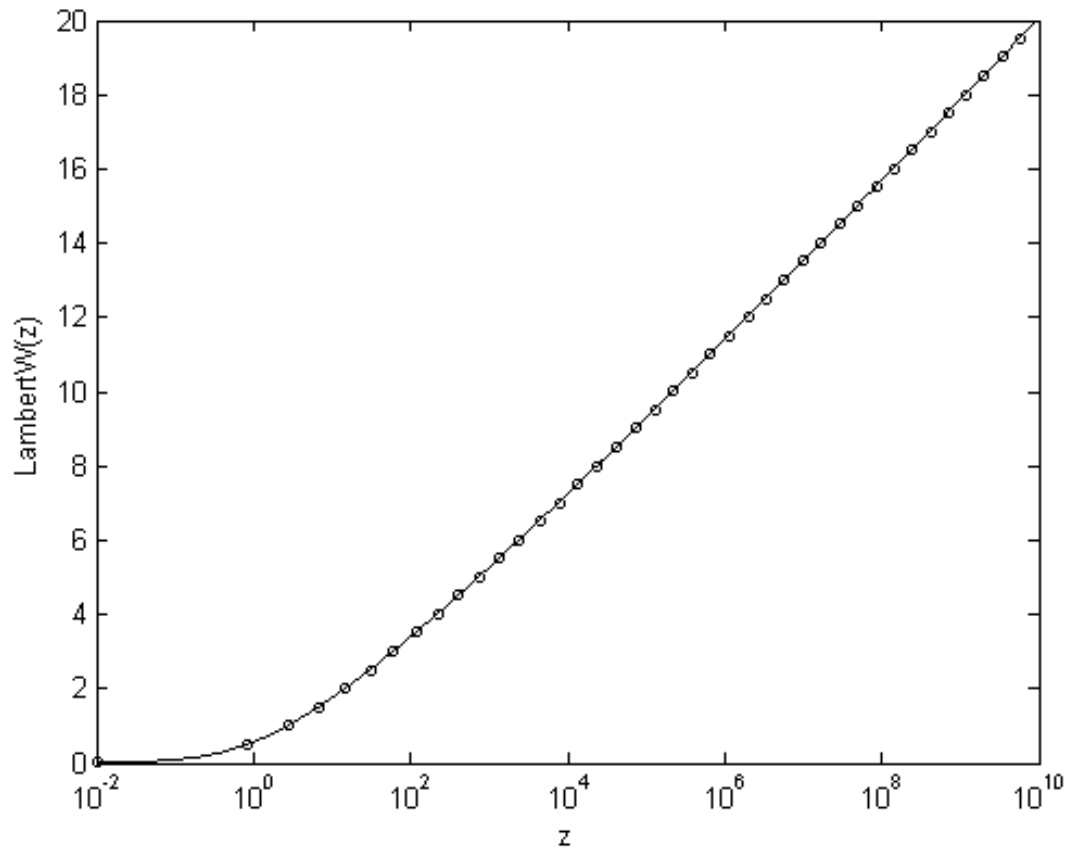
Iteration method (continues)

A comparison of the numerical and analytic solutions for $\Phi(z)$



Iteration method (continues)

A comparison of the numerical and analytic solutions for $LambertW(z)$



Iteration method (continues)

$$\beta_{(n+1)} = \Phi\left[\frac{1}{2r} \text{Lambert}W(2r \sin \beta_n e^v)\right]$$

- where $n=0,1,2,\dots$ with initial estimate

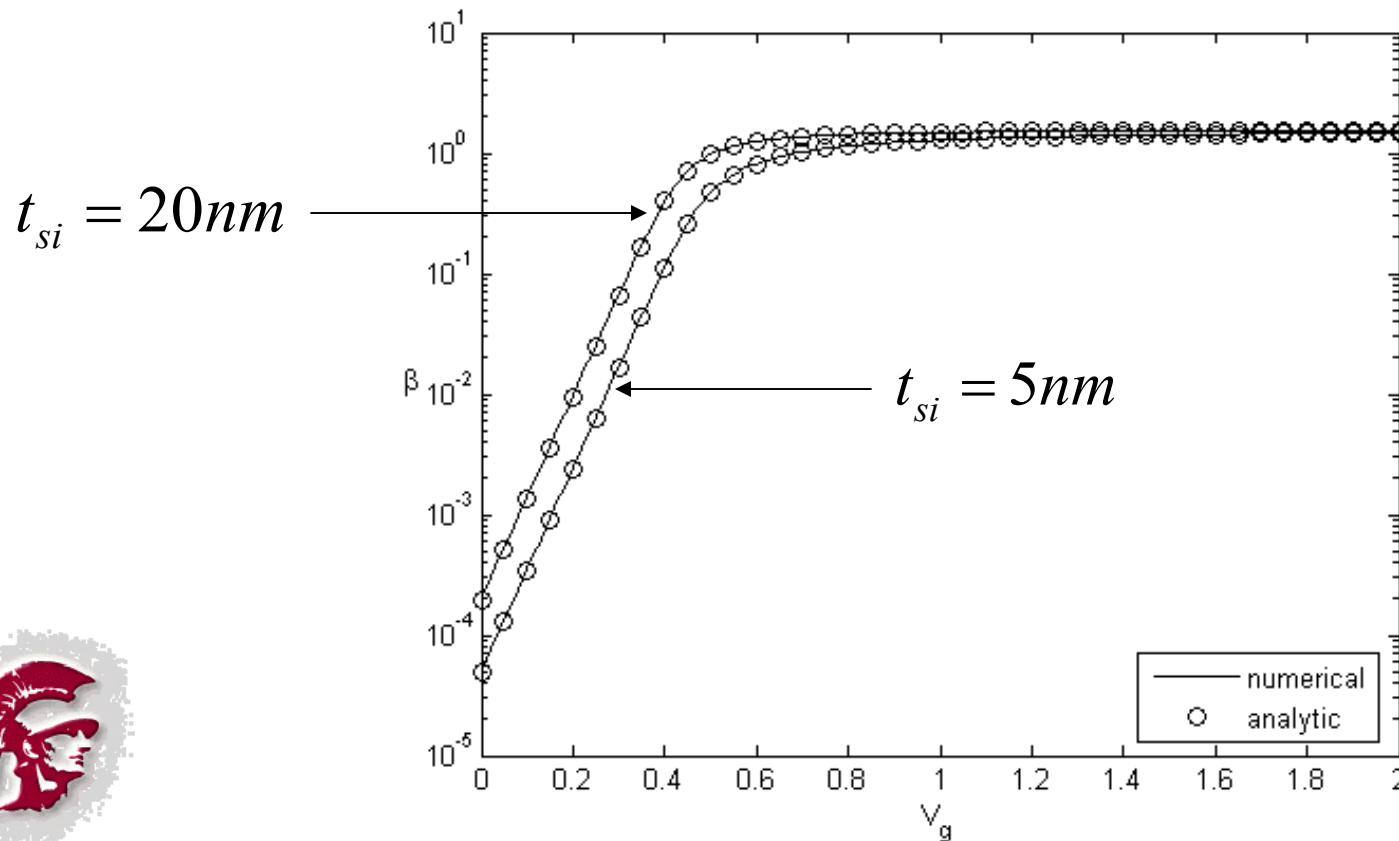
$$\beta_0 = \frac{e^{-v}}{(4r+1)} (-1 + \sqrt{1 + 2(4r+1)e^{2v}})$$

- four iterations \longrightarrow excellent results compared to the numerical



Iteration method (continues)

Comparison of the numerical and iterative solutions for β (four iterations)



Quantum model for DG

- Triangular potential well approximation.
- Considering the Schrödinger equation only along the longitudinal direction.
- Quantum effect on the semiconductor energy band gap and intrinsic density.



Quantum model for DG (continues)

- 1-D Schrödinger equation

$$\frac{d^2\psi_j}{dx^2} + \frac{2m^*}{\hbar^2}[E_j - U]\psi_j = 0$$

- Where $m^*=0.916m_e$ is electron effective mass in the direction perpendicular to the transistor channel surface, $U=-qF_s$ and F_s the surface field.



Quantum model for DG (continues)

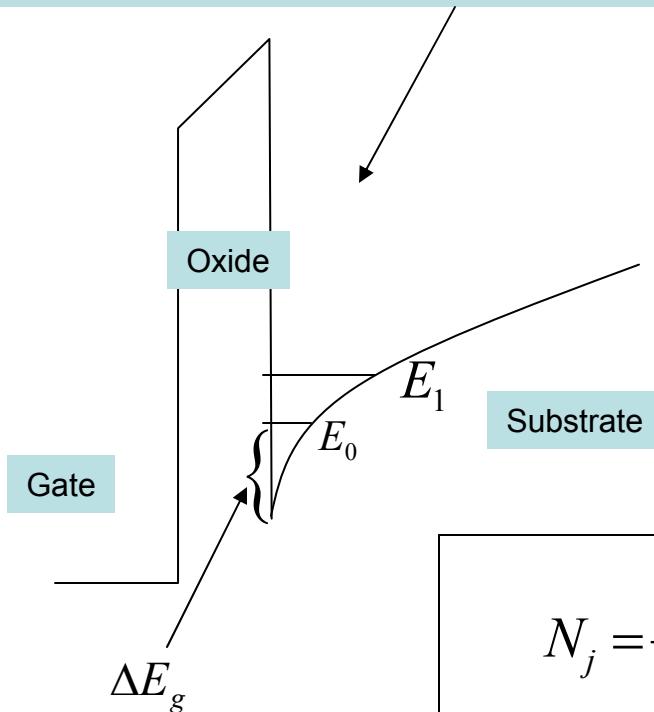
- Solving the eigenvalue problem gives the ***Airy functions*** as solutions for the Schrödinger equation with energy eigenvalues

$$E_j = \left(\frac{\hbar^2}{2m^*} \right)^{1/3} \left((3/2)\pi q F_s \left(j + \frac{3}{4} \right) \right)^{2/3}$$



Quantum model for DG (continues)

•Band structure near the surface



•The electron concentration in j_{th} sub-band:

$$N_j = \frac{0.38m_e}{\pi\hbar^2} \int_{E_j}^{\infty} \frac{dE}{1 + e^{(E-E_f)/kT}} = 0.38m_e \left(\frac{kT}{\pi\hbar^2} \right) \ln(1 + e^{(E_f-E_j)/kT})$$



Quantum model for DG (continues)

- Quantum effect on the intrinsic charge density

• Classical: →

$$n_i^c = 2 \left(\frac{kT}{2\pi\hbar^2} \right)^{\frac{3}{2}} (m_h m_e)^{\frac{3}{4}} e^{-E_g / 2kT}$$

• Quantum: →

$$n_i^q = e^{-\Delta E_g / 2kT} n_i^c$$



Quantum model for DG (continues)

- Quantum correction for the energy band gap

$$\Delta E_g = \frac{13}{9} \beta^* (\epsilon_{si} / 4kT)^{1/3} (F_{seff})^{2/3}$$

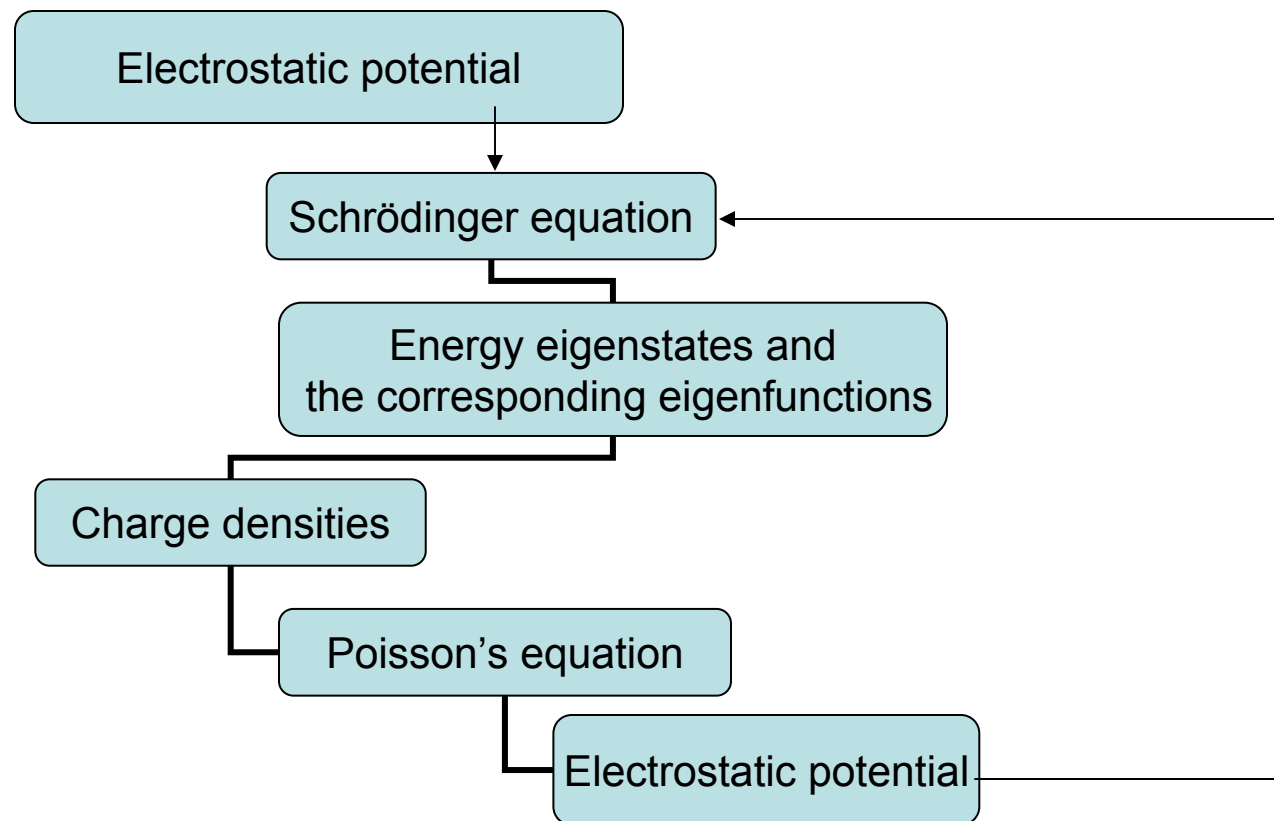
where $\beta^* = 6.6 \times 10^{-29} \text{ J} \cdot \text{m}$, $F_{seff} = \eta(V_g + V_t) / t_{ox}$,

$$V_t = V_{t0} + 2V_{th} \ln[q(V_g - V_{t0}) / 4rkT],$$

$$V_{t0} = \Delta\phi + 2V_{th} \ln\left[\frac{2}{t_{si}} \sqrt{2\epsilon_{si}kT / q^2 n_i^c}\right] \text{ and } \eta = 0.5$$

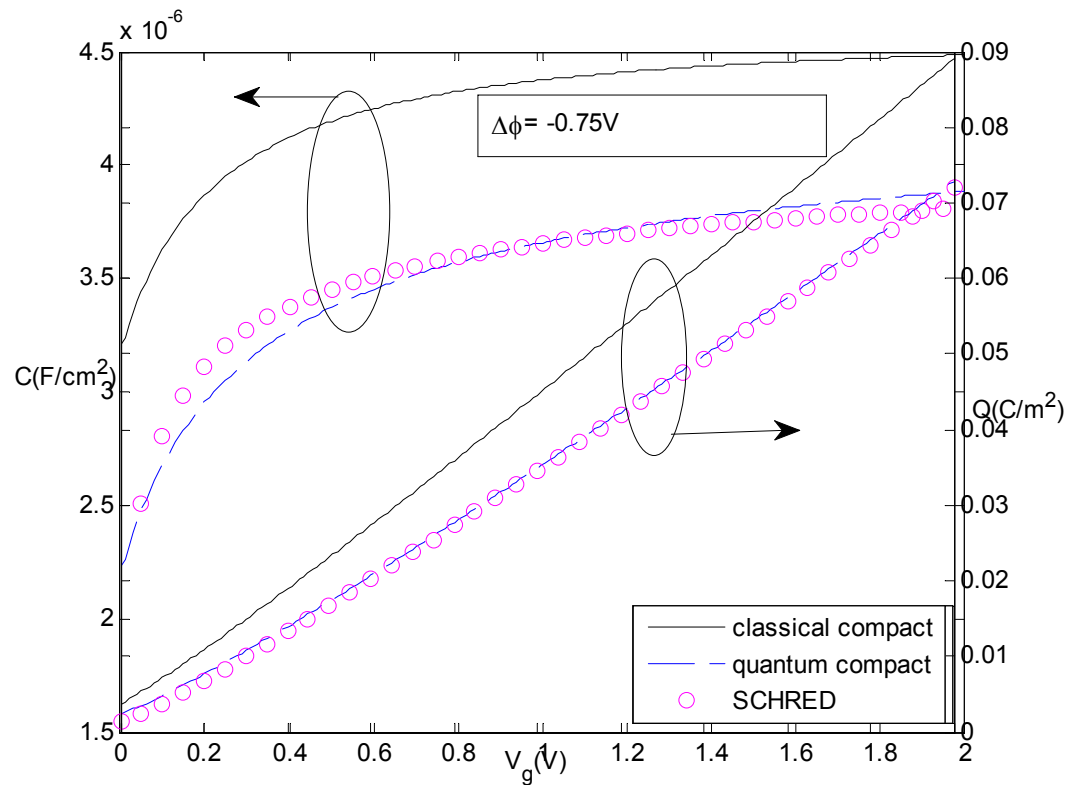


Self-Consistent Schrödinger-Poisson (SP) numerical approach



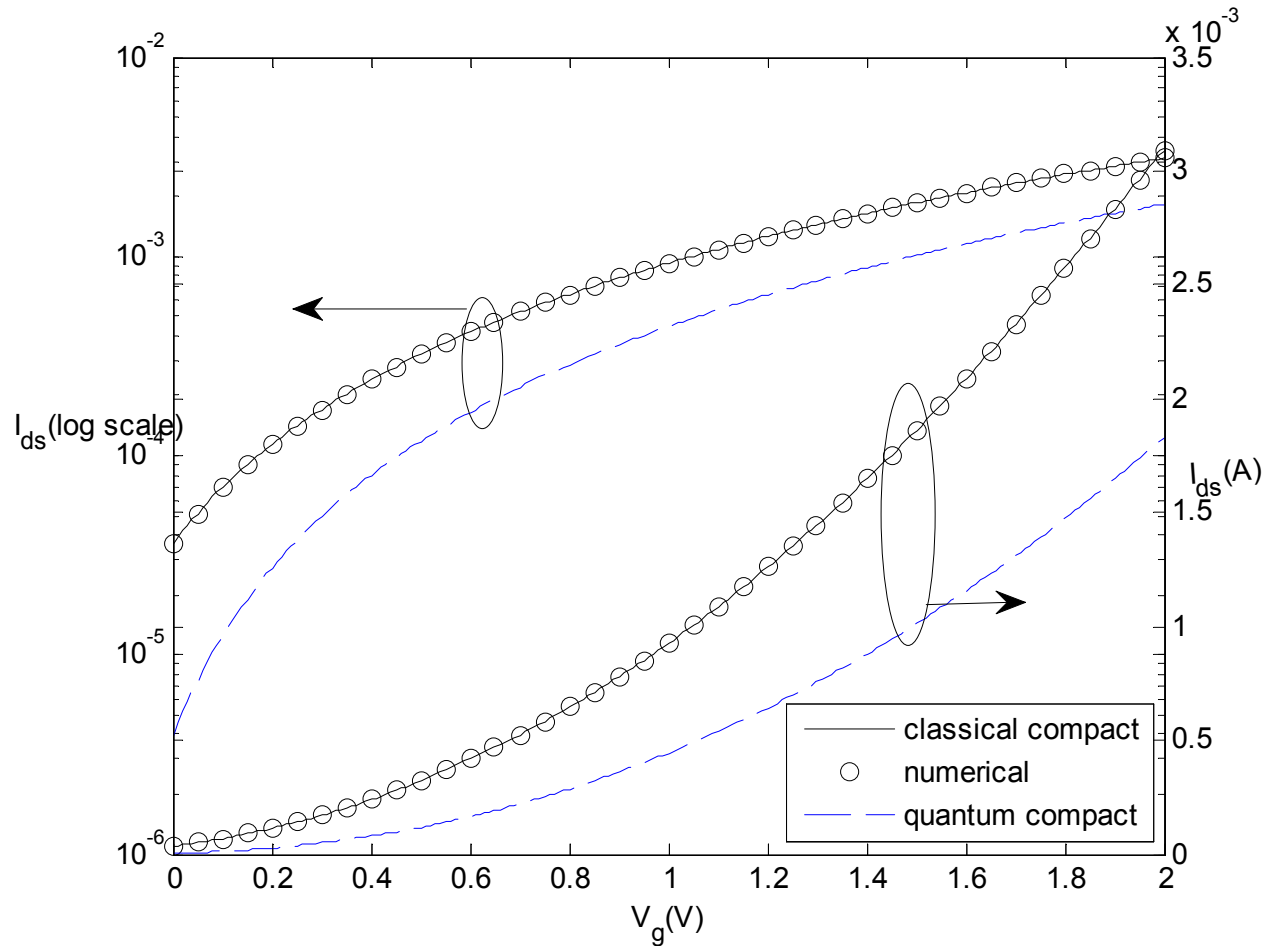
Results and comparison

Total mobile charge and gate capacitance versus gate voltage plots with 5nm silicon, 1.5nm oxide thicknesses.



Results and comparison

- Channel current versus gate voltage with $V_{ds}=2V$, 5nm silicon, 1.5nm oxide thicknesses and constant carrier mobility $\mu = 300 \text{ cm}^2 / V \cdot s$



Results and comparison

Channel current versus source-drain voltage with 5nm silicon and 1.5nm oxide thicknesses

